



FY11/3 Financial Results

Renesas Electronics Corporation

May 18, 2011

Yasushi Akao, President

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Thank you for visiting Renesas Electronics' earnings briefing for the fiscal year ended March 2011.

Before we begin, please be sure to review the cautionary statement on page 2.

(FOREWARD-LOOKING STATEMENTS)

FY10/3 consolidated results are sum of respective results of the former NEC Electronics Corporation and the former Renesas Technology Corp. The amount of "Net sales" and "Sales from semiconductors" are presented by rearranging the former Renesas Technology's sales account to adjust presentation to the former NEC Electronics' presentation. The statements in this presentation with respect to the plans, strategies and forecasts of Renesas Electronics and its consolidated subsidiaries (collectively "we") are forward-looking statements involving risks and uncertainties. We caution you in advance that actual results could differ materially from such forward-looking statements due to several factors. The important factors that could cause actual results to differ materially from such statements include, but are not limited to: general economic conditions in our markets, which are primarily Japan, North America, Asia and Europe; demand for, and competitive pricing pressure on, our products and services in the marketplace; our ability to continue to win acceptance of its products and services in these highly competitive markets; and movements in currency exchange rates, particularly the rate between the yen and the U.S. dollar. Among other factors, a worsening of the world economy; a worsening of financial conditions in the world markets, and a deterioration in the domestic and overseas stock markets, would cause actual results to differ from the projected results forecast.

Executive Summary

I . FY11/3 Financial Results

- ▣ Achieved operating profit for full-year through steady implementation of structural reforms and merger synergies, though net sales were below the company's expectation due to the impact of the Great East Japan Earthquake, etc.
- ▣ Recorded special loss of 118.2 billion yen from structural reforms and the impact of the earthquake

II . Impact of the Great East Japan Earthquake and Efforts toward Recovery

- ▣ Maximize product supply through early recovery of the Naka factory and by shifting production to alternate manufacturing sites
- ▣ Taking into account the impact of the earthquake, reduce investments and expenditures

Slide 3 provides an overview of the points we will discuss today.

First, we will explain financial results for the fiscal year ended March, 2011.

Net sales were below our estimate announced on January 29, 2011, mainly due to impact of the earthquake. However, we secured operating profit for full-year, achieving our primary target in the first year following the merger. This accomplishment was mainly due to steady implementation of structural reforms and merger synergies.

Also, we recorded special loss of 118.2 billion yen from impact of the earthquake, in addition to loss from structural reforms previously explained.

Second, we will explain the impact of the Great East Japan Earthquake and our efforts toward recovery.

We will explain details on our efforts for the worst-hit Naka factory in the following slides. Basic information is also available on Renesas press releases and notices.

I. FY11/3 Financial Results

Now let us discuss our financial results for the fiscal year ended March 2011.

FY11/3 Financial Snapshot

- Attained operating profit for full-year, achieving the first-year management goal following the merger
- Recorded special loss from earthquake in addition to structural reforms

(B yen)	FY11/3				
	Q4	QoQ	Full-year	Difference from original forecasts	YoY
Net Sales	275.3	+0.1	1,137.9	-12.1	+75.5
Semiconductor Sales	249.5	+5.0	1,018.9	-11.1	+76.4
Operating Income (Loss)	10.4	+7.0	14.5	+7.5	+127.8
Ordinary Income (Loss)	7.8	+6.7	1.0	+6.0	+126.4
Net Income (Loss)	-56.2	-38.6	-115.0	-35.0	+22.8
1US\$=	83 yen	No change	86 yen	-	-
1 Euro=	111 yen	1 yen strong	114 yen	-	-

(Note) The YoY figures indicate sum of respective results of the former NEC Electronics and the former Renesas Technology or difference from the reclassified figures.

Slide 5 shows the summary of the financial results for the fiscal year ended March 2011.

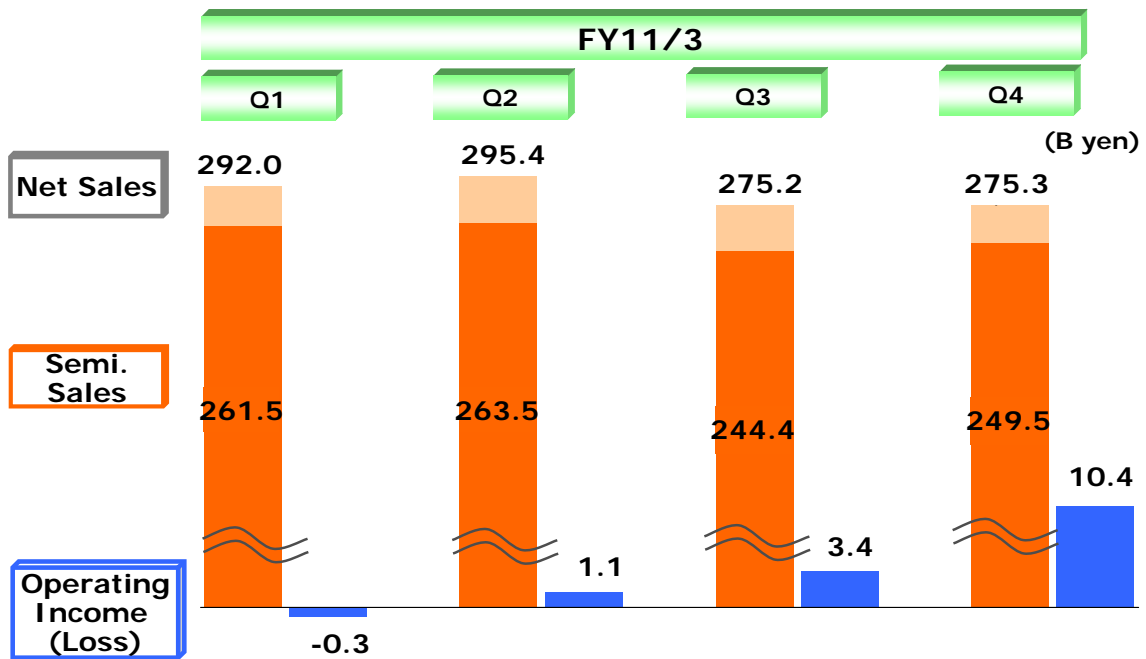
In the fourth quarter, semiconductor sales increased by 5 billion yen quarter on quarter. Operating income also increased by 7 billion yen

For the full-year, operating income increased significantly from the original forecasts to 14.5 billion yen. Ordinary income also turned into positive for the full-year. Net loss was 115 billion yen from recording special loss from impact of the earthquake in addition to a loss from structural reforms as previously mentioned.

We will explain more details in the following slides.

FY11/3 Quarterly Financial Results

■ Operating income improved on a quarter-by-quarter basis



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This slide shows trends in quarterly results.

Although net sales decreased in the second half due to the slowdown in the Japanese market, operating income showed improvements every quarter thanks to the structural reforms and merger synergies.

FY11/3 Semiconductor Sales

- Full-year sales of MCU and Analog & Power increased exceeding sales growth of that of total semiconductor

(B yen)	FY11/3		
	Q4	QoQ (%)	Full-year
Total Semiconductor Sales	249.5	+2%	1,018.9
MCU	95.0	+1%	384.1
Analog & Power	77.0	+6%	316.2
SoC	74.7	-2%	311.7
Other Semiconductors	2.7		6.9

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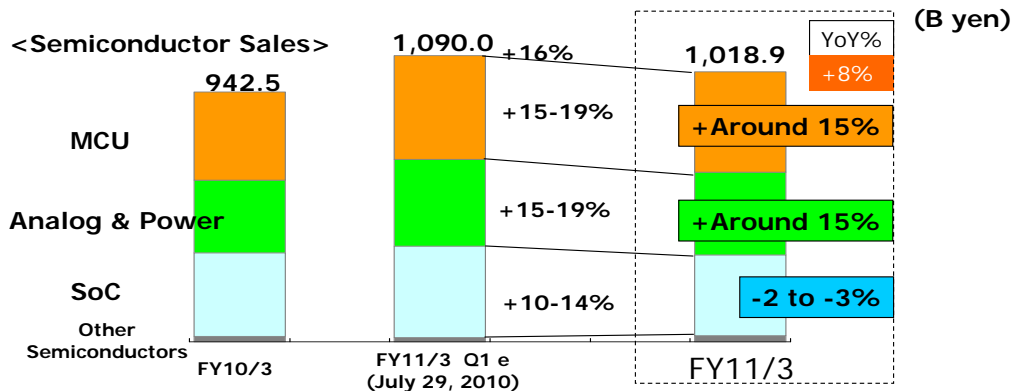
Slide 7 shows the breakdown of the fourth quarter and the full year sales by business unit.

In the fourth quarter, sales of analog & power in particular increased quarter on quarter.

For the full-year, sales of both MCU and analog & power increased exceeding the growth rate of the total semiconductor sales year on year. We will explain more details in slides 8 and 9.

FY11/3 Semiconductor Sales by Business

- Overseas market: Steady demand for automotive applications, image processing SoC and display drivers for smartphones in emerging countries including China
- Japanese market: Weak demand for automotive and consumer applications from the end of the first half as well as sluggish sales in mobile SoCs for feature phones
- Stronger yen caused a decrease of approximately 16 B yen in semiconductor sales
[1US\$=90 yen (forecast as of July 29) => 1US\$=86 yen]



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Slide 8 shows semiconductor sales in the year ended March 2011 in comparison with that of the previous year as well as our original forecast announced on July 29. The left bar shows the sales result of the year ended March 2010. The middle bar shows our Q1 forecast and the right bar shows the result of the year ended March 2011.

Regarding business breakdown, sales of MCU and Analog & Power were slightly lower than the original forecast, while SoC sales decreased from the forecast, despite our estimate to achieve a double-digit growth rate.

To explain results regionally, in overseas market especially for emerging countries like China, demands were steady for automotive MCUs, automotive power devices, image processing SoCs for smart phones, and display drivers for small & medium panels.

On the other hand in the Japanese market, demands for automotive and consumer applications decreased and sales of mobile SoCs for feature phones were also sluggish from the second quarter.

Compared with the forecast as of last July, stronger yen caused a decrease in sales in addition to market environment stated above.

FY11/3 Semiconductor Sales Breakdown by Business

	YoY	Major Factors
<p>MCU FY11/3 Sales Automotive approx. 45% General-purpose approx. 55%</p>	Automotive ↑	>Continuously secured the leading market share for automotive MCU worldwide after the merger
	General-purpose ↑	>Increased sales largely from strong industrial and consumer applications in emerging countries including China
<p>A&P FY11/3 Sales Compound Semiconductor approx. 15% Display driver IC approx. 20% Power Device & Analog IC approx. 65%</p>	Power device & analog IC ↑	>Increased sales of power devices and analog ICs from expanding automotive market in emerging countries and increased integration of electronic components
	Display driver IC ↓	>Struggled in display IC market for large LCD panels. Increased sales of smaller LCD drivers due to growth of smartphone market.
<p>SoC FY11/3 Sales Automotive approx. 10% Mobile approx. 35% Industrial approx. 10% PC peripheral approx. 15% Consumer approx. 30%</p>	Mobile ↓	>Significant decrease in sales of basedband processor due to sluggish demand in the Japanese feature phone market despite an increase in sales of image processor for camera phones
	Consumer ↓	
	PC peripheral ↓	
	Industrial ↑	>Decreased sales due to the weak PC peripherals (HDD, ODD) market
	Automotive ↑	

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Slide 9 shows details on the full-year semiconductor sales breakdown by business units.

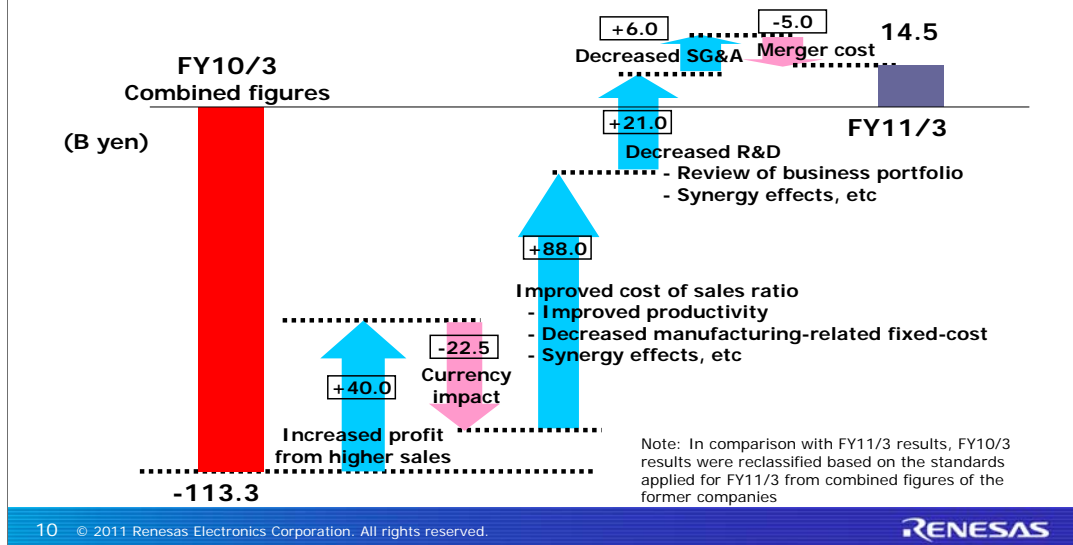
Sales of both automotive MCU and general-purpose MCU increased year on year. Especially, sales of MCUs for industrial and consumer applications in emerging countries including China went well.

As for analog & power device, sales of power device and analog IC increased year on year as automotive market expanded and the numbers of electronic components integrated in a car increased.

SoC business saw a significant decrease in sales on mobile SoC for Japanese feature phones and PC peripheral SoC year on year due to weak demand in PC market.

Factors Affecting FY11/3 Operating Income (Loss) YoY

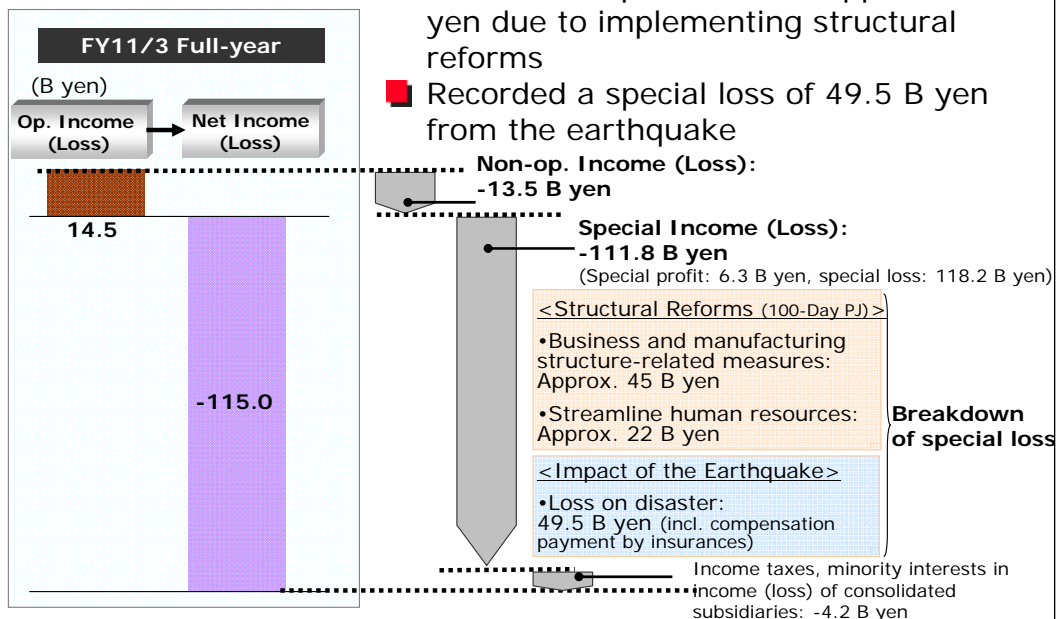
- Achieved full-year operating profit from: Increased sales, improved cost of sales ratio due to enhanced productivity, decreased depreciation cost through reduced capital investments, decreased R&D cost through streamlining the product portfolio



Slide 10 shows the factors affecting full-year operating income and loss in the fiscal year ended March 2011 in comparison with the previous year.

The fiscal year ended March 2010 recorded operating loss of 113.3 billion yen in combined figures of the former companies before the merger. However, as shown in the slide, the fiscal year ended March 2011 turned positive from significantly improving operating income by 127.8 billion yen. This was due to improved cost of sales ratio from enhanced productivity, decreased depreciation cost through suppressing capital investments, decreased research and development costs through streamlining product portfolio. These efforts in addition to increased sales contributed to achieving operating profit.

Factors Affecting FY11/3 Net Income (Loss)



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Slide 11 shows the factors affecting net loss in the fiscal year ended March 2011.

In addition to special loss of approximately 67 billion yen from structural reforms decided through the 100-Day project, we also recorded loss on disaster of 49.5 billion yen as a special loss due to the impact of the Great East Japan Earthquake.

The details on each special loss will be explained later.

As a result, net loss for the full-year was 115 billion yen.

Progress on the 100-Day Project (1) -Growth Strategy: Optimize Business Portfolio-

	Measures
MCU	<ul style="list-style-type: none"> •Consolidate and/or select process technology, CPU cores and peripheral IPs •Newly established a business organization led by a local representative from the subsidiary in China to capture market opportunities in China and other emerging markets •Plan to develop 1,000 new products for the Chinese market by 2012
	<ul style="list-style-type: none"> •Unify marketing functions of MCU Business and A&P Devices Business to reinforce direct promotions to global market
Analog & Power	<ul style="list-style-type: none"> •Expand product lineups and kit solutions mainly for automotive and power management applications •Enhance product lineups of power devices extending from low-voltage to high-voltage (Launch 1,000 products in 3 years)
SoC	<ul style="list-style-type: none"> •Established Renesas Mobile through acquisition of LTE modem technology from Nokia, promoting LTE modem platform business that is expected to expand W/W •Target social infrastructures including industrial and communication as focused domains and concentrate resources into those areas

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In the next section, we will explain our progress on the three-pronged business strategies formulated through the “100-Day project”.

This slide shows our measures based on the growth strategy by business.

For MCU business, we consolidated and selected overlapping process technologies, CPU cores and peripheral IPs of the former companies. We also established a new business organization led by a local representative within the subsidiary in China to capture market opportunities in the Chinese market, which is expected to expand further. We plan to develop 1,000 new MCU products for the Chinese market by 2012.

As for Analog & Power business, we expanded our product lineups and kit solutions mainly for automotive and power supply applications. Also, we unified marketing functions of MCU business and Analog & Power businesses to reinforce direct promotions to the global market.

Regarding SoC solutions business, we defined social infrastructures including industrial and communication applications as our focus segment and further concentrated resources onto it. Especially for mobile market, we established Renesas Mobile through acquisition of LTE modem platform for the mobile phone as well as to the convergence market that is expected to expand worldwide.

Progress on the 100-Day Project (2)

-Realization of merger synergies-

	Measures
Sales	<ul style="list-style-type: none"> •Strengthened sales channels by concentrating competitive distributors [30=>16 companies, Completed in FY11/3 Q3] •Integrated Renesas sales sites in Japan and other countries [38=>16 sites, Completed in FY11/3 Q3]
Design & Development	<ul style="list-style-type: none"> •Development of common platform for multimedia SoCs [Announced the first product (R-Car) in FY11/3 Q3] •Integration of CPU cores of low-end MCUs [5=>4 CPU core, Started sample shipment of the first MCU incorporating the new RL78 core in FY11/3 Q4] •Integration of product and technology roadmaps of the former companies through intensive benchmarks [Unify development structures for 28nm and below] •Reduce design cost by integrating development environment
Production	<ul style="list-style-type: none"> •Enhancement of capabilities to handle market fluctuations through “fab-network”, by utilizing foundries and sub-contractors, and by flexibly suppressing manufacturing-related fixed-costs •Miniaturization of chip size and package as well as reduction of testing time
Others	<ul style="list-style-type: none"> •Integration of logistics, warehouses and information system

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In slide 13, we will explain our measures to realize merger synergies.

First, we completed our plans to strengthen sales channels by concentrating competitive distributors in Japan and to integrate our overlapping global sales sites in the first year following the merger.

Second, for the design & development, we decided to develop common platform for multimedia SoCs and to integrate CPU cores of low-end MCUs.

For our manufacturing structure, we worked to enhance our capabilities to handle market fluctuations through “fab-network”, by utilizing foundries and sub-contractors, and by flexibly trimming manufacturing-related fixed-costs. Through intensive benchmarks of the former companies, we also enhanced our manufacturing efficiency from further miniaturization of chip size and package and reduction of testing time.

Furthermore, we promoted integration of our logistics, warehouses and information system.

Progress on the 100-Day Project (3)

-Implementation of Structural Reforms-

- Implemented structural reforms as planned despite a decrease in special loss by 10 billion yen from the previous forecast due to some measures with lower than estimated expenses and loss

	Measures
Business and manufacturing structural reforms: Approx. 45 B yen (Previous forecast: approx. 53 B yen)	<ul style="list-style-type: none"> Recorded impairment loss on fixed assets of the Tsuruoka factory and the Roseville factory Sold the Roseville Factory Realignment of production lines in Shiga (125mm wafer line is to be closed), Fukuoka (to be closed), and Kochi (Lent partial production space)
Optimize human resources: Approx. 22 B yen (Previous forecast: approx. 24 B yen)	<ul style="list-style-type: none"> Implemented early retirement program (Total of 1,487 employees retired as of March 31) Moved approximately 700 employees to distributors and major shareholder companies Promoted streamlining human resources with manufacturing-related structural reforms (including approximately 600 employees from the sale of the Roseville Factory) Shifted resources internally to focused business (approximately 1,000 employees)
Total : Approx. 67 B yen (Previous forecast: approx. 77 B yen)	

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Slide 14 shows structural reform measures and the amount of special loss recorded in the fiscal year ended March 31, 2011.

First, as for business and manufacturing structural reforms, we recorded impairment loss on fixed assets of the Tsuruoka factory and the Roseville factory in the first quarter. We also decided to sell the Roseville factory in March 2011.

We also realigned our production lines at our multiple manufacturing sites. As a result of these measures, we recorded a special loss of approximately 45 billion yen.

Second, in addition to our measures to streamline human resources, including early retirement program and the transfer to major shareholders and sales distributors, we also promoted to shift our human resources internally to focus segment.

As a result, we recorded special loss of approximately 22 billion yen.

We have previously announced that we were going to record a special loss of approximately 77 billion yen from implementing structural reform measures formulated through the "100-day project". However, the total amount of special loss decreased by 10 billion yen from the company's estimate due to some measures that resulted in less-than-expected expenses and loss. We have been implementing our structural reform measures as scheduled and there is no change to our plans even after the earthquake.

FY11/3 Balance Sheet

(B yen)	As of Apr. 1, 2010 (After the capital injection)	As of Dec. 31, 2010	As of Mar. 31, 2011
Total Assets	1,215.4	1,151.3	1,145.0
Cash and Cash Equivalents	337.7	334.3	337.3
Inventories	126.6	144.0	123.4
Liabilities	801.7	808.4	854.0
Interest-Bearing Debt	372.0	366.7	378.2
Shareholders' Equity	421.0	362.2	306.0
Net Assets	413.6	342.9	291.1
D/E Ratio (Gross)	0.91	1.09	1.33
D/E Ratio (Net)	0.08	0.09	0.12
Equity Ratio	33.5%	29.2%	24.8%

Note 1)

1. "Cash and Cash Equivalents": Sum of cash and deposits, and short-term investment securities minus the Time deposits with maturities of more than three months
2. "Interest-bearing debt": Short-term borrowings, Current portion of long-term borrowings, Current portion of bonds with share subscription rights, lease obligations, Bonds with share subscription rights, Long-term borrowings
3. "Equity": Shareholders' equity, Other Comprehensive Income
4. "D/E ratio (gross)": Interest-bearing debt / Equity
5. "Liabilities" as of April 1, 2010 (after the capital injection) includes negative goodwill

Note 2)

The balance of "April 1, 2010 after capital injection" includes adjustment related to the business combination transaction and 134.6 billion yen of capital increase through third-party allotment on April 1, 2010.

Slide 15 shows the company's balance sheet.

Inventories decreased by approximately 20 billion yen from the end of December 2010 to the end of March 2011. This was mainly due to decreased inventories of finished products and work-in-progress at Renesas Electronics and our sales subsidiaries resulting from the shutdown of the production lines from the earthquake, and loss on disposal of inventories from the earthquake.

As we recorded a special loss of 115 billion yen from structural reforms and the earthquake, our equity reduced significantly and the equity ratio was approximately 25%. However, the balance of cash and cash equivalents remained almost unchanged from that as of April after the capital injection. Net debt equity ratio was 0.12, still remaining at a low level .

FY11/3 Cash Flows

- Achieved positive free cash flows for the full-year by reducing capital investments

(B yen)	FY11/3				
	Q1	Q2	Q3	Q4	Full-year
Cash Flows from Operating Activities	-2.0	35.0	53.9	15.6	102.5
Cash Flows from Investing Activities	-14.4	-18.4	-39.0	-24.0	-95.8
Free Cash Flows	-16.4	16.6	15.0	-8.4	6.7

Slide 16 shows cash flows.

We secured positive free cash flows for the fiscal year ended March 31, 2011 mainly due to reduced investments.

II. Impact of the Great East Japan Earthquake and Efforts toward Recovery

In the next section, we will explain the impact of the Great East Japan Earthquake and our efforts toward recovery.

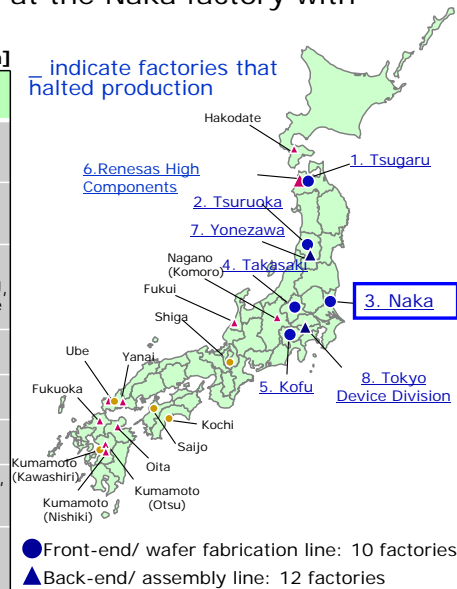
Recovery Status of the Factories Affected by the Earthquake

- Resumed production at all manufacturing sites except the Naka factory
- Plan to restart production (wafer input) at the Naka factory with limited production capacity from June

[Recovery status of the factories that shutdown production]

	Factory	Operational Status	Major Products
Front-end	1. Tsugaru Factory, Renesas Northern Japan Semiconductor	Restarted manufacturing	Automotive MCU
	2. Tsuruoka Factory, Renesas Yamagata Semiconductors	Restarted manufacturing	General-purpose IC, SoC
	3. Naka Factory, Renesas Electronics	Stopped production, Planning to restart partial production in June	General-purpose MCU, Automotive MCU, General-purpose IC, SoC
	4. Takasaki Factory, Renesas Electronics	Restarted manufacturing	Power device, Analog IC
Back-end	5. Kofu Factory, Renesas Electronics	Restarted manufacturing	Power device, Analog IC
	6. Renesas High Components (Aomori)	Restarted manufacturing	General-purpose IC
	7. Yonezawa Factory, Renesas Northern Japan Semiconductor	Restarted manufacturing	Automotive MCU, General-purpose MCU
	8. Tokyo Device Division, Renesas Eastern Japan Semiconductor (Oume)	Restarted manufacturing	RF ICs

indicate factories that halted production



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Slide 18 shows our recovery status of the factories that were forced to shut their production from the earthquake.

Due to the earthquake that occurred on March 11, our five front-end factories and three back-end factories shut production temporarily.

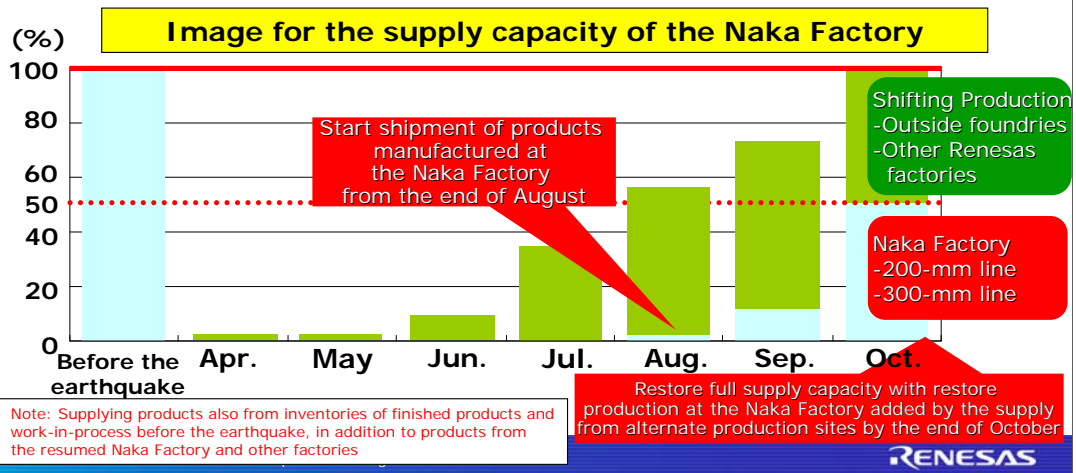
However, thanks to great support from inside and outside the Renesas Group helping to speed up the recovery, we have been able to restore normal production at all of these factories other than the Naka factory that was closest to the epicenter and was therefore damaged the most.

As for the Naka factory, we plan to restart production with limited capacity from the beginning of June 2011.

We will explain more details on the recovery schedule of the Naka factory and also on our plans to shift production in the following slides.

Schedule of Naka Factory Recovery and Alternate Productions

- Restore the Naka Factory, giving top priority to meet supply (to attain 100% supply capability) of products originally manufactured at the factory before the earthquake
- Plan to restore supply capacity of the Naka Factory to that of pre-earthquake levels by the end of October with additional supply from other factories and outside foundries



This slide shows the schedule for the Naka factory recovery and plans on alternate productions.

For products that were originally manufactured at the Naka factory, we will make it a top priority to fulfill the product supply.

By proceeding product supply from the Naka factory and product supply from the alternate manufacturing sites in parallel, we expect we will be capable of restoring product supply to that of pre-earthquake levels at 100 percent by the end of October with additional supply from other factories and outside foundries.

Other than the supply from the Naka factory and the alternate manufacturing sites shown on the diagram, we will also supply products from finished goods already in stock and work-in-process goods in the assembly lines.

However, although we will be capable of covering part of the loss through these stocks and work-in-process goods until May, we are afraid we are going to be forced to be in a state of supply shortage. We are communicating closely with our customers to obtain understanding of this situation.

We were able to move up the recovery schedule of the Naka factory and we will continue to work at earnest toward recovery giving the highest priority securing product supply for our customers.

Acceleration of the “Fab-Network”

- Further accelerate “fab-network” based on the experience through the earthquake to be resistant to demand fluctuations and accidents
- Enhance “fab-network” by promoting product development on the premise that “fab-network” would be applied

< Examples of “fab-network” for the Naka Factory >

Naka Factory	Other production sites of Renesas Group	Foundry
200mm line	<ul style="list-style-type: none"> ➢ Tsugaru Factory/ Renesas Northern Japan Semiconductor ➢ Saijo Factory/ Renesas Electronics 	➢ GLOBAL FOUNDRIES
300mm line	<ul style="list-style-type: none"> ➢ Tsuruoka Factory/ Renesas Yamagata Semiconductors ➢ Saijo Factory/ Renesas Electronics 	➢ TSMC

Almost half of the products manufactured at the Naka Factory before the earthquake can be manufactured at other factories

Slide 20 shows our “fab-network” strategy following the earthquake.

We have been promoting our “fab-network” strategy from before, we were able to quickly resume production at alternate manufacturing sites. And in response to the Great East Japan Earthquake, we will continue to further enhance our “fab-network” strategy as a mean to strengthen our manufacturing structure to become resistant to demand fluctuations and unexpected accidents.

By further promoting the “fab-network” we will construct a flexible manufacturing structure that is capable of adjusting to fluctuations to advance the formulation of strong business structure that could achieve a stable growth.

The diagram on this slide shows one example of an adoption of “fab-network” of the Naka factory.

Following the earthquake, we have shifted about half of its production at the Naka factory to some of the Group’s other factories and outside foundries.

Financial Impact from the Great East Japan Earthquake

- Estimate a loss from earthquake to total 65.5 B yen
- Recorded special loss on disaster of 49.5 B yen for the year ended March 31, 2011, with 16 B yen compensated by insurance income receivable

Breakdown	Amount
Repair cost of fixed assets	43.1 B yen
Loss on disposal of inventories	7.3 B yen
Loss on disposal of fixed assets	6.2 B yen
Fixed costs during the temporary shutdown period of operations	5.9 B yen
Loss on cancellation of lease contracts and Others	3.0 B yen
Sub total for loss on disaster	65.5 B yen
Insurance income receivable	-16.0 B yen
Total	49.5 B yen

Naka Factory accounted for approx. 85% of the overall loss

In the next section, we will explain details on special loss from the earthquake.

As shown in the chart, the special loss comes mainly from repair cost of fixed assets, which accounted for approximately 70 percent of the overall loss, and other loss including loss on disposal of inventories and fixed costs during the temporary shutdown period of operations.

As a result, we recorded a loss on disaster of 49.5 billion yen for the year ended March 2011 including an insurance income receivable of 16 billion yen, and estimated a loss from the earthquake to total 65.5 billion yen.

Recovery Plans Against the Impact of the Earthquake

- Focus every possible efforts on recovery work to minimize negative impacts on the business results

Impact on the business results

- Sales (production)
 - ✓ Impacts caused by production shutdown
 - ✓ Impacts on procuring raw materials and components
 - ✓ Uncertainty of market growth from impacts of the earthquake
- Profit
 - ✓ Lower profit from decreased sales (production)
 - ✓ Expenses incurred for recovery
 - ✓ Loss during the temporary shutdown period of operations

Measures

[Short-term measures]

- Minimize negative impacts on the sales (Early recovery of the Naka Factory, and shifting production to alternate production sites)
- Reduce capital investment
- Streamline R&D expenses
- Reduce every expenses
- Secure funds required for recovery

[Mid-term measures]

- Further promote structural reforms
- Overhaul of BCP (Business Continuity Plan)

In slide 22, we will explain impact of the earthquake on our business, and our countermeasures.

As for impact on our sales and production, in addition to shutdown of the manufacturing lines and decreased production capacity, there were also impacts on procurement of raw materials and uncertain market condition.

As for impact on our income, in addition to decreased sales and production, there would be recovery-related expenses and continue to expect loss from temporary shutdown to result in lower profit.

As an countermeasure, we have already talked about our measures to recover Naka factory and to shift production alternate manufacturing sites and outside foundries to minimize impacts on our sales.

In addition to these measures, we will reduce capital investments, streamline our R&D cost, and as a emergency measure trim down all costs including manufacturing-related fixed costs.

Additionally, we will further accelerate concentration of our resources on growing businesses and

strengthen our business structure. Based on what we have learnt from the earthquake, we will overhaul our BCP

to construct a structure capable of quickly restoring product supply for our customers and minimizing impact to our corporate earnings

FY12/3 Forecasts

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Next, we will explain the company's outlook for the fiscal year ending March 2012.

FY12/3 Forecasts

- The Great East Japan Earthquake caused damages to Renesas Electronics Group's multiple manufacturing sites and has brought uncertainty to market conditions surrounding Renesas Electronics
- Therefore, due to difficulty in specifying reasonable forecasts at this moment, Renesas Electronics did not announce the consolidated forecasts today. The company plans to announce the FY12/3 forecasts in July, 2011.
- Renesas Electronics also plans to hold a press conference in the beginning of July to explain its business strategy based on the business operation during the first year after the merger as well as the impact of the earthquake

As previously explained, the Great East Japan Earthquake brought damages to our multiple factories and has brought uncertainty to market surrounding us.

Therefore, due to difficulty in specifying reasonable forecasts at this moment, we did not announce the financial forecasts for the fiscal year ending March, 2012 today. We plan to announce the forecasts in July.

We also plan to hold a press conference in the beginning of July to explain our business strategy based on business operation during the first year after the merger as well as impacts of the earthquake.

Summary

Summary

- **Achieved full-year operating profit in FY11/3**
- **Promoted structural reform measures formulated through the 100-day project as scheduled**
- **Implement all possible measures to minimize financial impact from the Great East Japan Earthquake**

Slide 26 shows the summary of today's presentation.

First, we attained a full-year operating profit in the fiscal year ended March 31, 2011, successfully achieving our target of the first year following the merger.

Second, our structural reform measures formulated through the 100-day project are in progress as scheduled.

Lastly, the Renesas group suffered damages especially on the Naka factory from the Great East Japan Earthquake.

However, thanks to the dedicated support from inside and outside Renesas Group, we have been able to see the light of recovery at all of our damaged factories. We would like to take this opportunity to express our gratitude to all of you involved in the support of the Naka factory..

We are implementing all possible measures to minimize financial impact from the earthquake, giving top priority to secure product supply to our customers.



Thank you very much for your continued support of Renesas Electronics.

This concludes our presentation today.